NAKAGAWA -- 09/654,412 Client/Matter: 007324-0273795

IN THE ABSTRACT OF THE DISCLOSURE:

Please delete the present Abstract of the Disclosure and replace it with the following new Abstract of the Disclosure:

A component mounting circuit board includes a circuit pattern including a plurality of electrically conductive plates, an inner electrical component electrically connected to the circuit pattern, a resin molded section made of a resin by way of molding so as to cover the circuit pattern and the inner electrical component, the resin molded section having an opening allowing an outer electrical component located outside the resin molded section to be connected to the circuit pattern through the opening, and a metal member embedded in the resin molded section so as to be located to correspond to a portion of the inner electrical component and electrically insulated from the circuit pattern, the metal member being provided with an exposed portion exposed outside the resin molded section.